



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN Number:	20260806001.1	PCN Issued	August 07, 2026
Qualification of RFAB as an additional Fab site option, Die Revision, Datasheet, BOM update and MLA, CDAT as an additional Assembly site options for select devices		Sample request deadline:	October 06, 2026
		Estimated 1st ship date:	November 05, 2026
Sample requests received after October 06, 2026 will not be supported.			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling Design Data Sheet/Electrical Specification Wafer Fab Site Wafer Fab Material Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of RFAB as an additional Fab site option, BOM update & MLA, CDAT as additional Assembly site options for the devices listed below.

Current Fab Site			Additional Fab site		
Current Fab Site	Process	Wafer Diameter	Additional Fab site	Process	Wafer Diameter
FFAB	ASLNONC10	200mm	RFAB	LBC9	300mm

The die was also changed as a result of the process change.

Construction differences are as follows:

Group 1 device

	Current BOM	Additional BOM
Wire bond diam/type	0.96mil Au	0.8mil Cu

*Remain on current assembly site

Group 2 device

	Current Site	Additional Site
Assembly/Test site	FMX	MLA
Wire bond diam/type	0.96mil Au	0.8mil Cu

Group 3 device

	Current Site		Additional Site
	CRS*	MLA	CDAT
Assembly/Test site	1.0mil Cu	0.96milCu	0.8mil Cu
Wire bond diam/type	435143	4205846	4207123
Mount compound	441086	4208625	4222198
Mold compound	NiPdAu	Matte Sn	NiPdAu
Lead finish			

*Applicable to SN74CBTLV3257RGYR device

Data sheet update

The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.



SN74CBTLV3257

SCDS040N – DECEMBER 1997 – REVISED JULY 2026

Changes from Revision M (July 2018) to Revision N (July 2026)	Page
• Added additional applications.....	1
• Updated Thermal ratings	5
• Added Electrical Specification section for new package	7
• Added Switching Specification section for new package.....	8
• Added Typical Curves	8



SN74CBTLV3253

SCDS039K – DECEMBER 1997 – REVISED JULY 2026

Changes from Revision J (January 2018) to Revision K (July 2026)	Page
• Added New Packages with 125°C capability	4
• Updated Thermal ratings.....	5
• Added Electrical Specification section for new package.....	6
• Added Switching Specification section for new package	7
• Added Typical Curves	7



SN74CBTLV3251

SCDS054J – OCTOBER 2003 – REVISED JULY 2026

Changes from Revision I (October 2003) to Revision J (July 2026)	Page
• Added Applications section, Device Information table, Pin Configuration and Functions section, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
• Updated Thermal ratings.....	4
• Added Electrical Specification section for new package.....	5
• Added Switching Specification section for new package.....	5
• Added Typical Curves	6

Product Folder	Current Datasheet Number	New Datasheet Number	Link to full datasheet
SN74CBTLV3257	SCDS040M	SCDS040N	http://www.ti.com/product/SN74CBTLV3257
SN74CBTLV3253	SCDS039J	SCDS039K	http://www.ti.com/product/SN74CBTLV3253

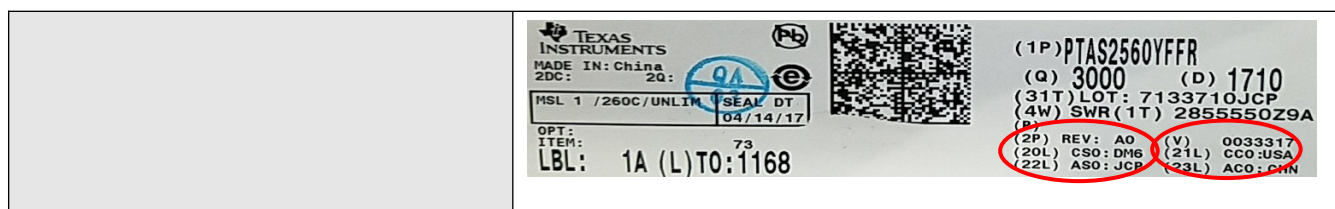
SN74CBLTV3251	SCDS054I	SCDS054J	http://www.ti.com/product/SN74CBLTV3251
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Qual details are provided in the Qual Data Section.

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:	Supply Continuity
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Anticipated impact on Form, Fit, Function, Quality or Reliability:	These devices include new die based on existing schematics in a larger diameter wafer fab with a die shrink. There are changes in the electrical tables. Physical aspects of the device have changed. Request the Supporting Data Packet (SDP) for more details on the changes. Evaluating samples is encouraged.																																						
Impact on Environmental Ratings	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings. <table><tr><th>RoHS</th><th>REACH</th><th>Green Status</th><th>IEC 62474</th></tr><tr><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td><td>☒ No Change</td></tr></table>	RoHS	REACH	Green Status	IEC 62474	☒ No Change	☒ No Change	☒ No Change	☒ No Change																														
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☒ No Change	☒ No Change	☒ No Change	☒ No Change																																				
Changes to product identification resulting from this PCN:	Fab Site Information <table><tr><td>Chip Site</td><td>Chip Site Origin Code (20L)</td><td>Chip Site Country Code (21L)</td><td>Chip Site City</td></tr><tr><td>FFAB</td><td>TID</td><td>DEU</td><td>Freising</td></tr><tr><td>RFAB</td><td>RFB</td><td>USA</td><td>Richardson</td></tr></table> Die Rev: <table><tr><td>Current</td><td>New</td></tr><tr><td>Die Rev [2P]</td><td>Die Rev [2P]</td></tr><tr><td>- , A</td><td>A</td></tr></table> Assembly Site Information <table><tr><td>Assembly Site</td><td>Assembly Site Origin (22L)</td><td>Assembly Country Code (23L)</td><td>Assembly City</td></tr><tr><td>FMX</td><td>MEX</td><td>MEX</td><td>Aguascalientes</td></tr><tr><td>CRS</td><td>CRS</td><td>MYS</td><td>Ipoh</td></tr><tr><td>CDAT</td><td>CDA</td><td>CHN</td><td>Chengdu</td></tr><tr><td>MLA</td><td>MLA</td><td>MYS</td><td>Kuala Lumpur</td></tr></table> Sample product shipping label (not actual product label):	Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City	FFAB	TID	DEU	Freising	RFAB	RFB	USA	Richardson	Current	New	Die Rev [2P]	Die Rev [2P]	- , A	A	Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City	FMX	MEX	MEX	Aguascalientes	CRS	CRS	MYS	Ipoh	CDAT	CDA	CHN	Chengdu	MLA	MLA	MYS	Kuala Lumpur
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CRS	CRS	MYS	Ipoh																																				
CDAT	CDA	CHN	Chengdu																																				
MLA	MLA	MYS	Kuala Lumpur																																				



Group 1 Products Affected:

SN74CBTLV3257PW R	SN74CBTLV3251PWRG 4	SN74CBTLV3257DR
SN74CBTLV3251DR	SN74CBTLV3253DR	SN74CBTLV3257PWRG 4
SN74CBTLV3251PWR	SN74CBTLV3253PWR	

Group 2 Products Affected:

SN74CBTLV3251DBQ R	SN74CBTLV3253DBQ R	SN74CBTLV3257DBQ R
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Group 3 Products Affected:

SN74CBTLV3251RGYR	SN74CBTLV3253RGYR	SN74CBTLV3257RGYR
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Group 1 Qualification Report

Approve Date 15-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3257DR	Qual Device: SN74CBTLV3253DR	Qual Device: SN74CBTLV3251DR	QBS Reference: TLV6258DBVR	QBS Reference: TLC3555QDRQ1	QBS Reference: LP2551-500DRQ1M3	QBS Reference: SN74LVC165ADRIQ1	QBS Reference: SN74CBTLV3251PWR	QBS Reference: SN74CBTLV3253PWR	QBS Reference: SN74CBTLV3257PWR
HAST	A2	Biased HAST	130C	96 Hours	-	-	-	-	-	-	-	-	-	-
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	1/770	-	1/770	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	-	1/770	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	1/770	-	1/770	1/770	-	-	-	-
TC	A4	Temperature Cycle	-65/150C	500 Cycles	-	-	1/770	-	-	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	1/770	-	1/770	1/770	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1450	1450	-	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	-	-	-	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/2310	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/30000	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	1/150	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	1/100	1/100	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/30	1/30	1/30	-	-	-	1/30	1/30	1/30	1/30
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/30	1/30	1/30	1/30
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	1/30	1/30	1/30	1/30
CHAP	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	-	-	-	-	1/300	1/300	1/300	1/300

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3257DR is qualified at MSL1 260C

Qual Device SN74CBTLV3253DR is qualified at MSL1 260C

Qual Device SN74CBTLV3251DR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2406-045

Qualification Report

Approve Date 14-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACBTLV3251PWR	Qual Device: SN74ACBTLV3253PWR	Qual Device: SN74ACBTLV3257PWR	QBS Reference: SN74HC874QPWQRQ1	QBS Reference: SN74AAC1245QPWQRQ1	QBS Reference: SN74AC595PWQRQ1	QBS Reference: CAHCT1GL3WDTXRQ1	QBS Reference: SN74AHG1G3WDTXRQ1	QBS Reference: CAHCT1G32WDTXRQ1	QBS Reference: SN74AC165PWQRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/770	1/770	1/770	1/770	3/2310
UHAIST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	3/2310	-	1/770	-	-	-
UHAIST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	1/770	-	1/770	1/770	3/2310
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/2310	1/770	1/770	1/770	1/770	3/2310
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	1/450	1/450	1/450	1/450	1/450
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/2310	-	-	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/24000	-	-	-	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	3/450	-	-	-	1/150	-	1/150
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/300	1/100	1/100	1/100	1/100	3/300
ESD	E2	ESD CDM	-	1000 Volts	1/30	1/30	1/30	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	2000 Volts	1/30	1/30	1/30	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/30	1/30	1/30	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/300	1/300	1/300	-	-	-	-	-	-	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3251PWR is qualified at MSL1 260C

Qual Device SN74CBTLV3253PWR is qualified at MSL1 260C

Qual Device SN74CBTLV3257PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2501-045

Group 2 Qualification Report

Approve Date 14-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74ACBTLV3251DBQR	Qual Device: SN74ACBTLV3253DBQR	Qual Device: SN74ACBTLV3257DBQR	QBS Reference: SN74ALV244AQDSRQ1	QBS Reference: TLV4812QDSRQ1	QBS Reference: TLV4812QDSRQ1	QBS Reference: SN74AC124AQDSRQ1	QBS Reference: TLV344CACL11DBVR	QBS Reference: SN74CBTLV3251PWR	QBS Reference: SN74CBTLV3253PWR	QBS Reference: SN74CBTLV3257PWR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	1/770	3/2310	1/770	-	-	-	-	-
UHAIST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	1/770	-	-	-	-	-	-	-
UHAIST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/2310	1/770	-	-	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	1/770	3/2310	1/770	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	1/450	3/2310	-	-	-	-	-	-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-	-	-	1/770	1/450	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	-	3/2310	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	-	3/24000	-	-	-
SD	C3	PB Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/150	-	1/150	-	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/150	-	1/150	1/150	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	-	-	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	1/100	-	1/100	1/100	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/30	1/30	1/30	-	-	-	-	1/30	1/30	1/30	1/30
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	-	1/30	1/30	1/30	1/30
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	-	1/30	1/30	1/30	1/30
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	-	-	1/300	1/300	1/300	1/300

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3251DBQR is qualified at MSL1 260C

Qual Device SN74CBTLV3257DBQR is qualified at MSL2 260C

Qual Device SN74CBTLV3253DBQR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Group 3 Qualification Report

Approve Date 14-July-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SN74CBTLV3251RGYR	Qual Device: SN74CBTLV3253RGYR	Qual Device: SN74CBTLV3257RGYR	QBS Reference: TLV62568DBVR	QBS Reference: SN74HCS245QKSRQ1	QBS Reference: SN74AC165WBQBRQ1	QBS Reference: SN74CBTLV3251PWR	QBS Reference: SN74CBTLV3253P
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	1/77/0	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	3/231/0	1/77/0	-	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	1/45/0	1/45/0	-	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/3000/0	-	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs ±15 minutes)	-	-	-	-	-	-	1/15/0	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	1/10/0	-	-
ESD	E2	ESD CDM	-	1000 Volts	1/3/0	1/3/0	1/3/0	-	-	-	1/3/0	1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	-	-	1/3/0	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	1/3/0	1/3/0
CHAR	E5	Electrical Characterization	Min, Typ, Max Temp	-	-	-	-	-	-	-	1/30/0	1/30/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	-	1/30/0	1/30/0

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74CBTLV3251RGYR is qualified at MSL2 260C

Qual Device SN74CBTLV3253RGYR is qualified at MSL2 260C

Qual Device SN74CBTLV3257RGYR is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2406-046

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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